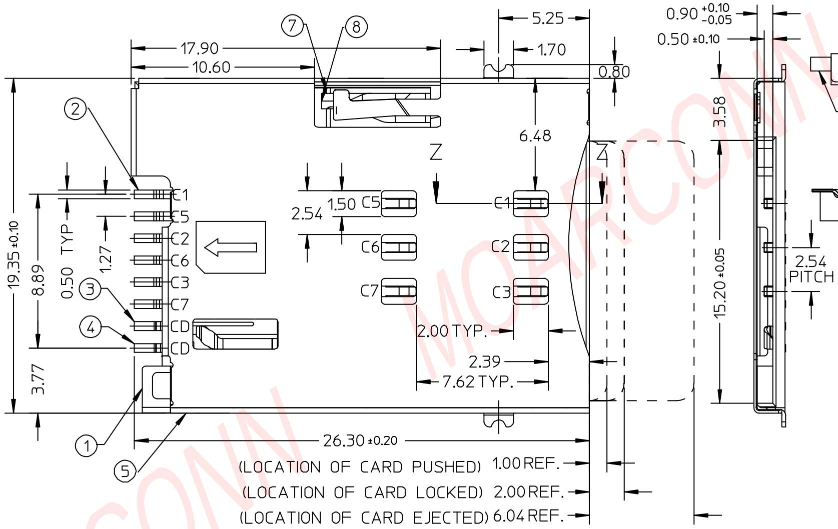
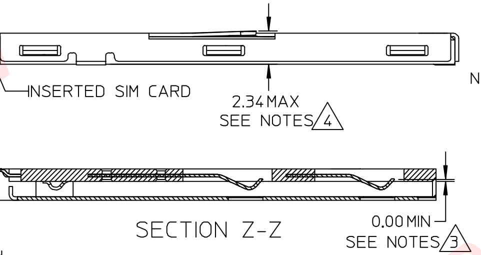
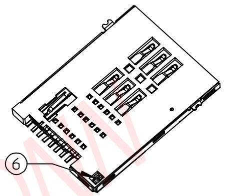
All materials,plating and process meet HF requirements.

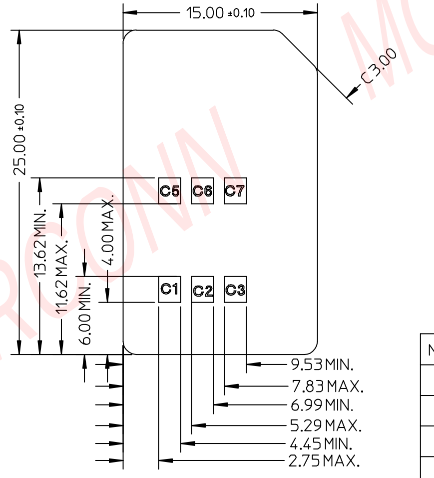






NOTES

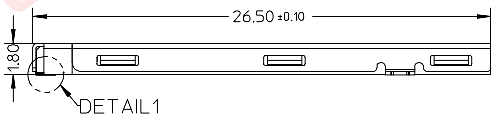
1. FINISH
   - 1-1 TERMINAL :
     - 50~200μ" NICKEL UNDER PLATED
     - 15μ" MIN GOLD PLATING ON CONTACT AREA
     - 3μ" MIN GOLD FLASH ON SOLDERING AREA
   - 1-2 SHELL :
     - 50~200μ"NICKEL UNDER PLATED
     - 3μ" MIN GOLD FLASH ON SOLDERING AREA
   - 1-3 DETECT PIN :
     - 50~200μ" NICKEL UNDER PLATED
     - 3μ" MIN GOLD PLATING ON CONTACT AREA
     - 3μ" MIN GOLD FLASH ON SOLDERING AREA
2. DETECT SWITCH: INSERT CARD=ON (NORMAL=OPEN)
3. I.E.,TERMINAL TIP WILL SINK INTO HOUSING.
4. SPRING RISE UP DURING PUSH-PUSH PERIOD
5. PRODUCT COMPLIANT TO ROHS DIRECTIVE 2011/65/EU AND ELV DIRECTIVE 2000/53/EC
6. SOLDERTAIL(10X) COPLANARITY 0.10MM MAX (BEFORE REFLOW)



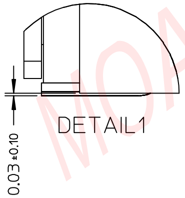
APPLICABLE CARD SIZE
THICKNESS:0.76+/-0.08

CARD INSERTED — WITHOUT CARD

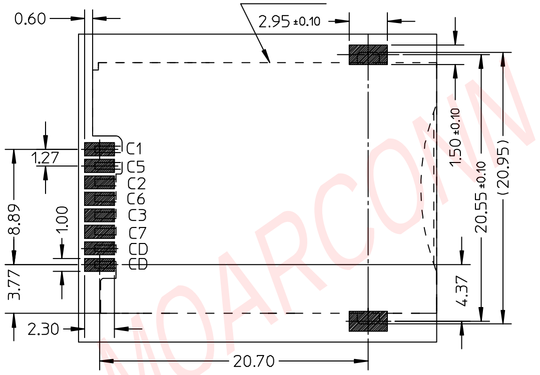
NO.	DESCRIPTION	Q'TY	MATERIAL
1	HOUSING	1	HIGH TEMPERATURE THERMOPLASTIC
2	TERMINAL	6	COPPER ALLOY
3	DETECT PIN LOWER	1	COPPER ALLOY
4	DETECT PIN UPPER	1	COPPER ALLOY
5	SHELLL	1	STAINLESS STEEL
6	COIL SPRING	1	PIANO WIRE
7	HEART CAM	1	HIGH TEMPERATURE THERMOPLASTIC
8	CAM PIN	1	STAINLESS STEEL



CONNECTOR PROFILE



DETAIL1



RECOMMENDED PCB LAYOUT
TOLERANCE +/-0.05MM

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	-------	NEW RELEASE	Zhangli	2025.1.4

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DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.10
X.XX: ±	0.05
X.XXX: ±	0.02
ANGULAR: ±	1°

PRODUCT NAME : SIM Card H1.8 push-push SMT	DRAWING: Zhangli	DATE: 2025.1.4
PRODUCT NO. : SM180-T5153-01-W	CHECK: /	DATE: /
DRAWING NO. : D-SM180-T5153-01-W	APPROVED:	DATE:

SCALE:	DWG ID:	REV.:	PAGE:
1:1	P D	X0	1 OF 1